

SOT1301-1

HLLGA16, thermal enhanced low profile land grid array package, 16 terminals, 1.42 mm pitch, 8 mm x 8 mm x 1.3 mm body

2 July 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HLLGA16
Package style descriptive code	HLLGA (thermal enhanced low profile land grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-01-2018
Manufacturer package code	SOT1301

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
seated height	1.25	1.3	1.4	mm
nominal pitch	-	1.42	-	mm
actual quantity of termination	-	16	-	



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2 Package outline

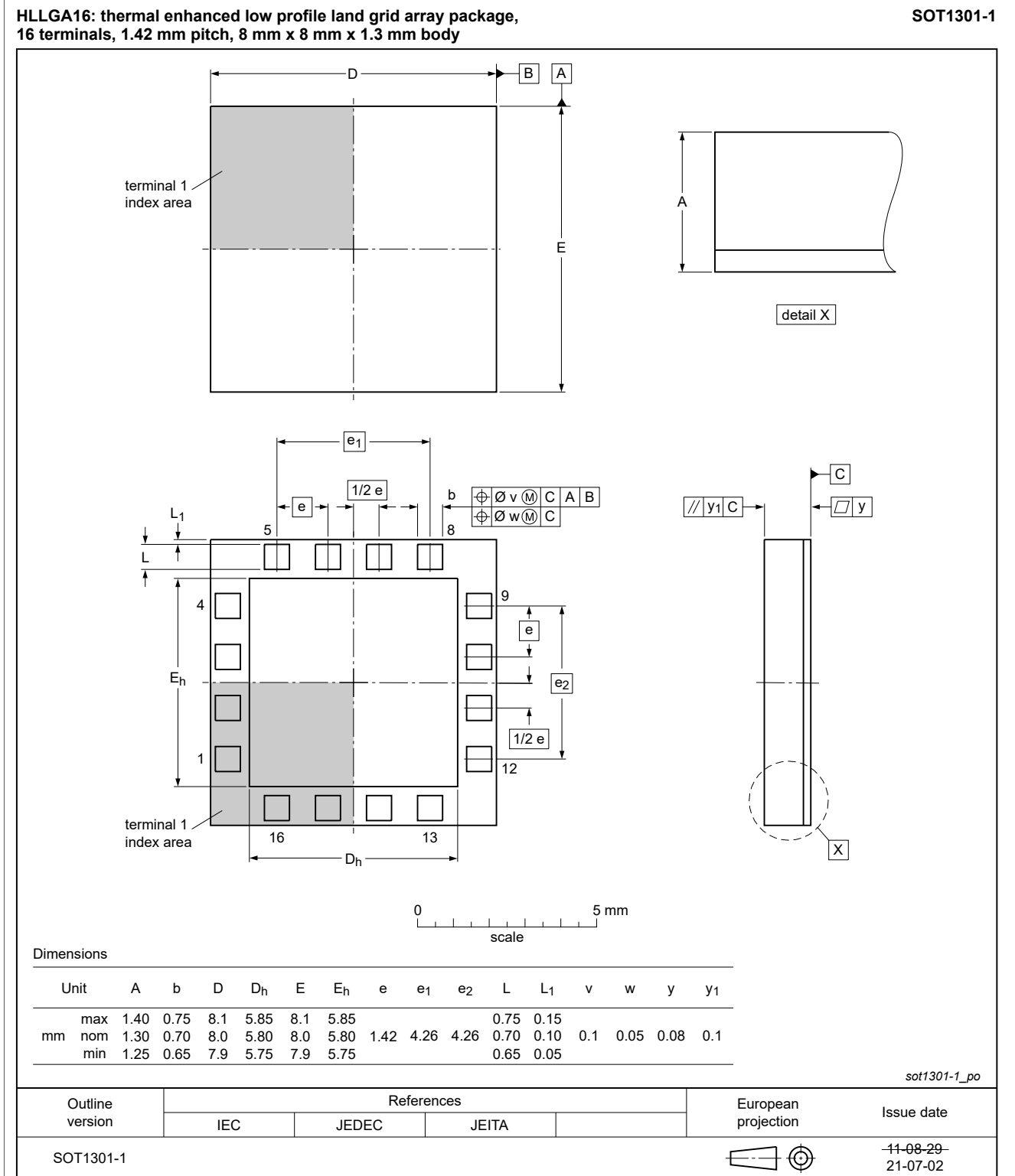
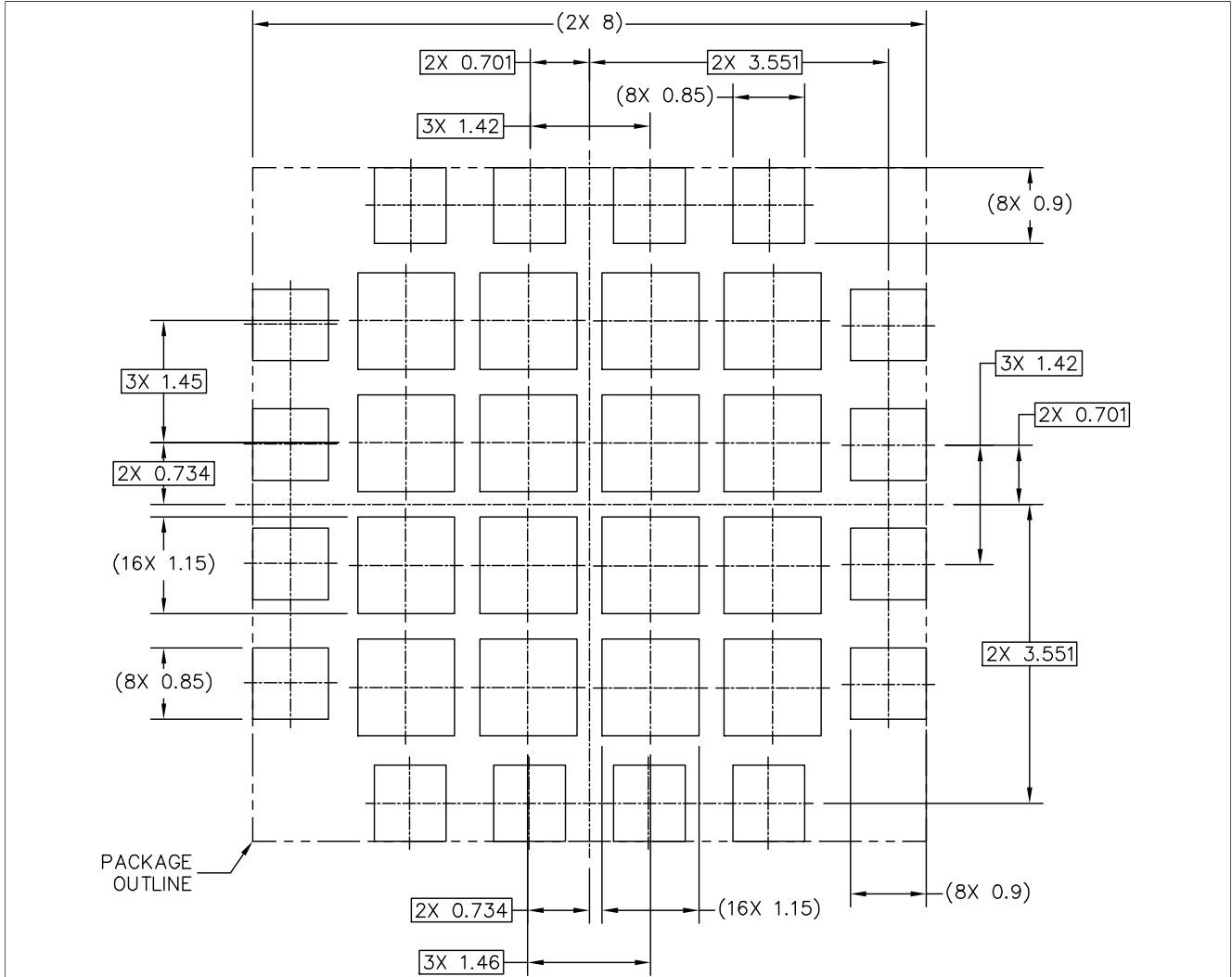


Figure 1. Package outline HLLGA16 (SOT1301-1)

HLLGA16, thermal enhanced low profile land grid array package, 16 terminals, 1.42 mm pitch, 8 mm x 8 mm x 1.3 mm body

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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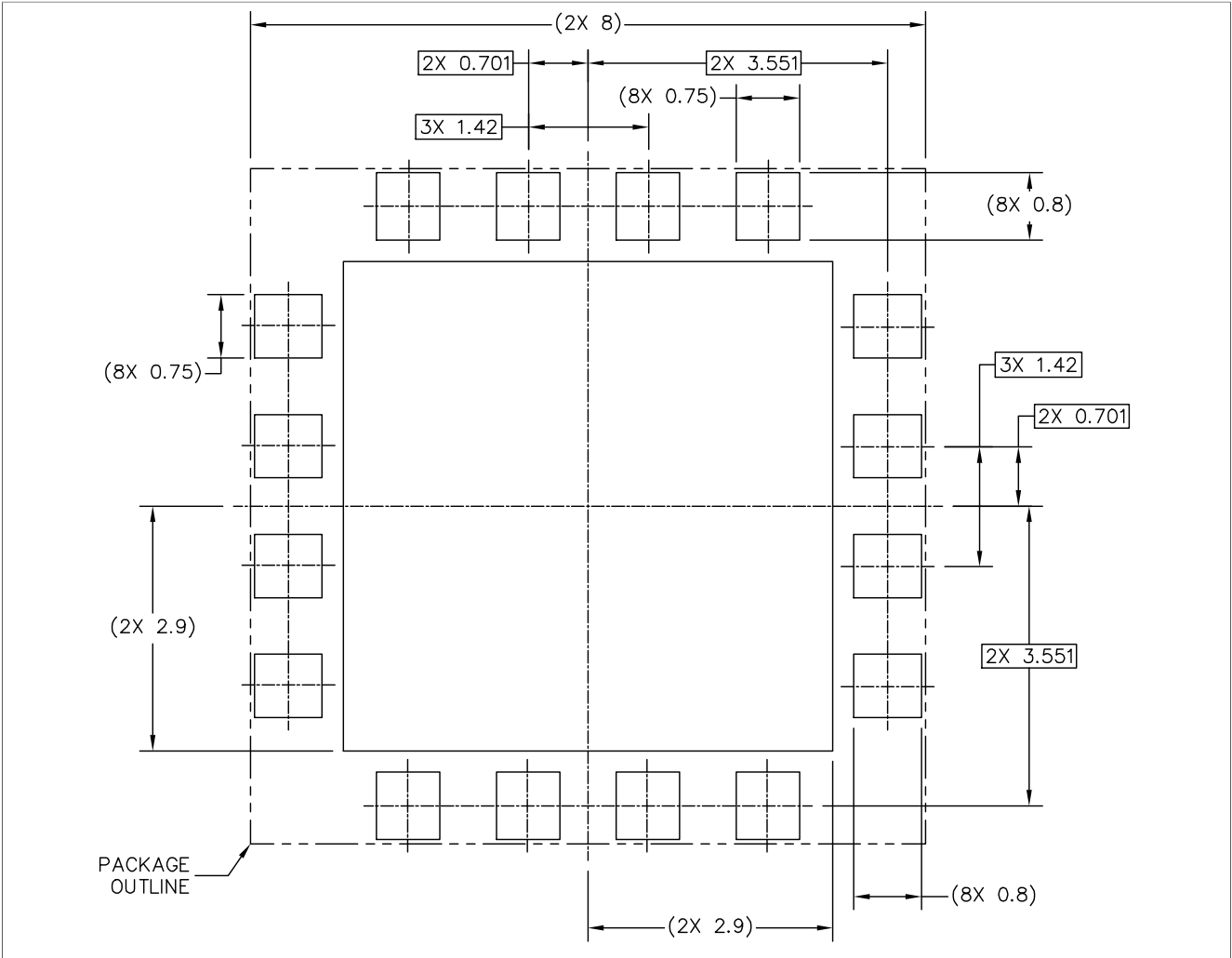
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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1301-1	REVISION: 0
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Figure 2. Reflow soldering footprint part1 for HLLGA16 (SOT1301-1)

HLLGA16, thermal enhanced low profile land grid array package, 16 terminals, 1.42 mm pitch, 8 mm x 8 mm x 1.3 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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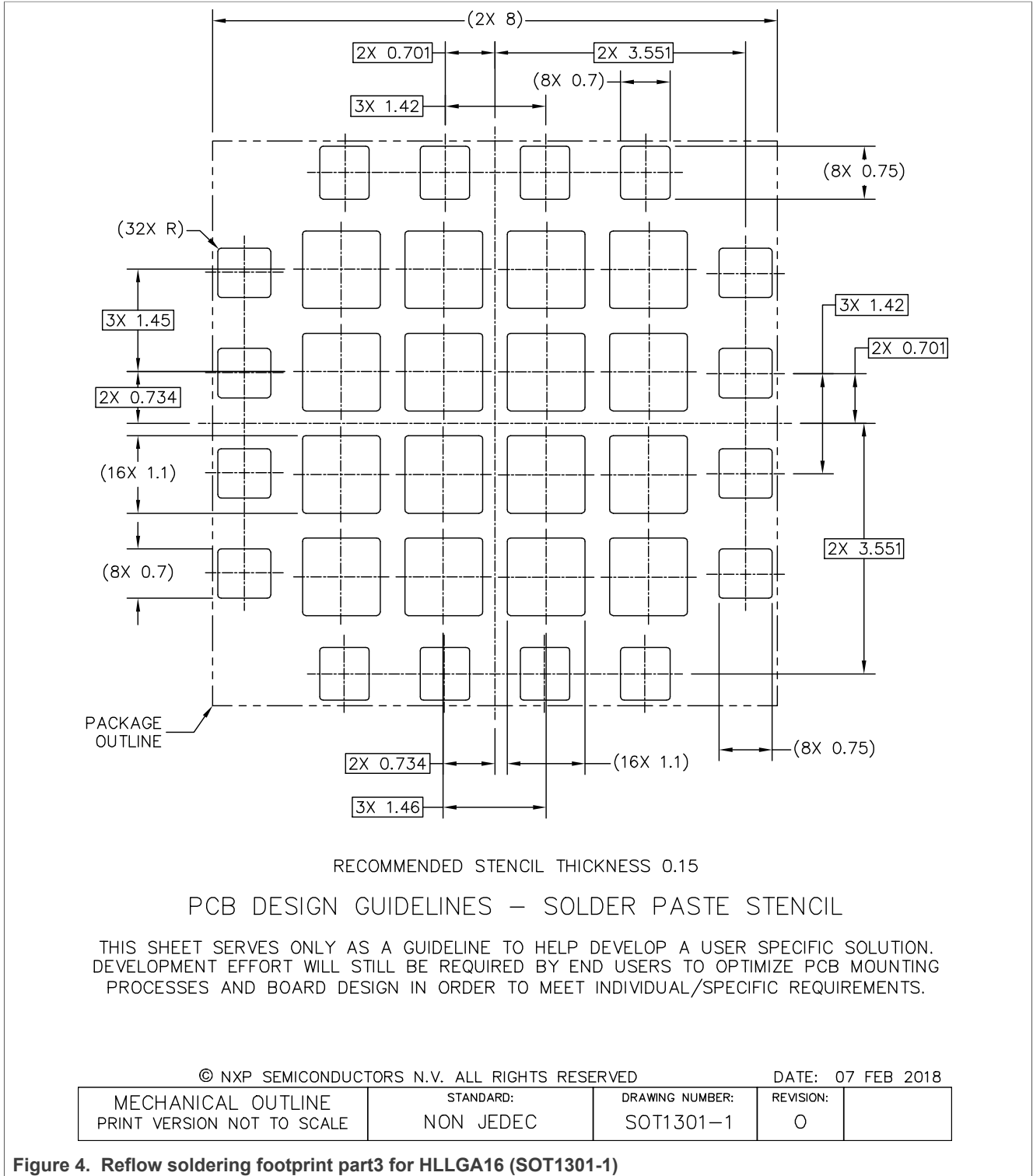
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Figure 3. Reflow soldering footprint part2 for HLLGA16 (SOT1301-1)

HLLGA16, thermal enhanced low profile land grid array package, 16 terminals, 1.42 mm pitch, 8 mm x 8 mm x 1.3 mm body



4 Legal information

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